

L Number	Hits	Search Text	DB	Time stamp
1	2376	thermoplastic near10 particulate	USPAT; US-PGPUB	2004/01/25 21:33
2	229	thermoplastic near10 (particulate powder) near10 (sinter sintered sintering)	USPAT; US-PGPUB	2004/01/25 22:09
3	35	tool near10 semiconductor near10 ceramic	USPAT; US-PGPUB	2004/01/25 23:05
6	112	wire adj bonding adj capillary	USPAT; US-PGPUB	2004/01/25 23:06
7	5	(wire adj bonding adj capillary) same ceramic	USPAT; US-PGPUB	2004/01/25 23:23
-	2784	((wire adj bonding adj capillary) same ceramic) same (diameter radius)	USPAT; US-PGPUB	2004/01/25 23:10
-	2784	((wire adj bonding adj capillary) same ceramic) and (diameter radius)	USPAT; US-PGPUB	2004/01/25 23:10
10	112	(wire adj bonding adj capillary)	USPAT; US-PGPUB	2004/01/25 23:30
11	0	((wire adj bonding adj capillary)) near10 micron	USPAT; US-PGPUB	2004/01/25 23:24
13	4	((wire adj bonding adj capillary)) near10 ceraMIC	USPAT; US-PGPUB	2004/01/25 23:25
14	32	(wire adj bonding adj capillary)	EPO; JPO; DERWENT; IBM TDB	2004/01/25 23:42
-	6886	semiconductor near10 tool near10 (hole borehole)	USPAT; US-PGPUB	2004/01/25 23:41
-	6886	(semiconductor adj tool) near10 (hole borehole)	USPAT; US-PGPUB	2004/01/25 23:41
-	6886	(semiconductor adj tool) near5 (hole borehole)	USPAT; US-PGPUB	2004/01/25 23:41
-	219322	(semiconductor adj tool)	USPAT; US-PGPUB	2004/01/25 23:42
-	219322	semiconductor adj tool	USPAT; US-PGPUB	2004/01/25 23:42
-	219322	semiconductor adj tool	USPAT; US-PGPUB	2004/01/25 23:43